Connector for microSD™ Card (Push-push Type)

SCHA Series



Compact low-profile type most suitable for mobile phones.

For SD Memory Card

For microSD™ Card

For SIM Card 8pins

For W-SIM

For Memory Stick Micro™

For Memory Stick™

Combine Type

For Compact Flash™

For CMOS Camera Module

NEW	

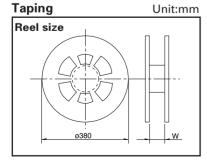
Typical Specifications

	Items		Specifications		
Structure -	Applicable media		microSD™ Card		
	Mounting type		Surface mounting type		
	Mounting style		Standard mount/ Reverse mount		
	Media ejection structure		Push-push type		
Performance –	Operating temperature range		−20°C to +70°C		
	Voltage proof		500V AC 1minute		
	Insulation resistance (Initial)		1,000MΩ min.		
	Contact resistance (Initial)	Connector contacts	100mΩ max.		
		Detection switch	500mΩ max.		
	Insertion and removal cycle		5,000cycles		

Product Line

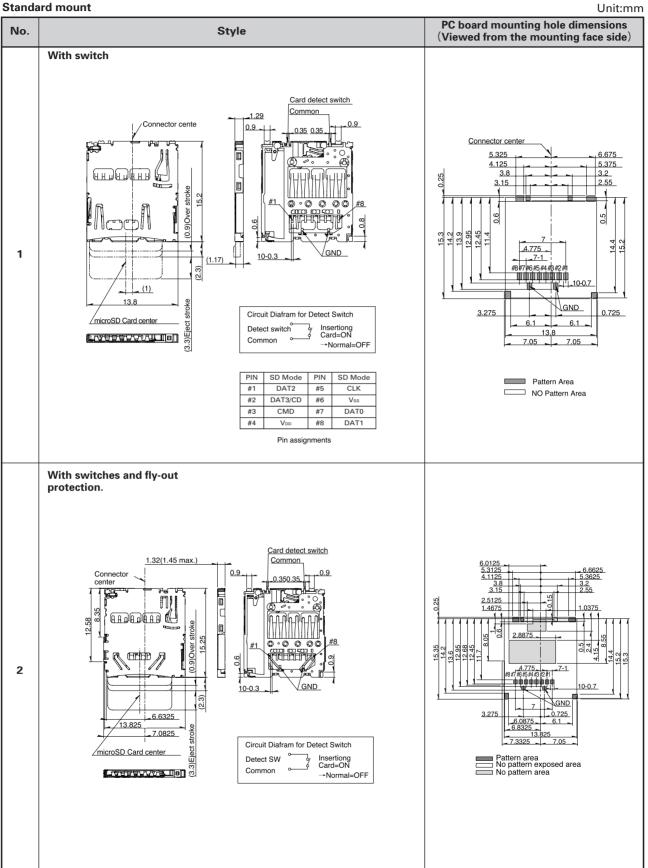
Media ejection structure	Mounting system	Features	Stand-off (mm)	Packing system	Product No.	Drawing No.
Push-push type	Standard mount	With switch	0	Taping	SCHA4B0100	1
		With switches and fly-out protection.			SCHA4B0400	2
	Reverse mount	With switch			SCHA5B0200	3

■ Packing Specifications



Product	Number of packages (pcs.)			Reel width	Tape width	Export package	
No.	1 reel	1 case /Japan	1 case /export packing	W (mm)	(mm)	measurements (mm)	
SCHA4B0100	2,000	6,000	12,000			100 100	
SCHA4B0400	2,000	0,000	12,000	24.4	24	403×403× 249	
SCHA5B0200	1,500	4,500	9,000			2-70	

Dimensions



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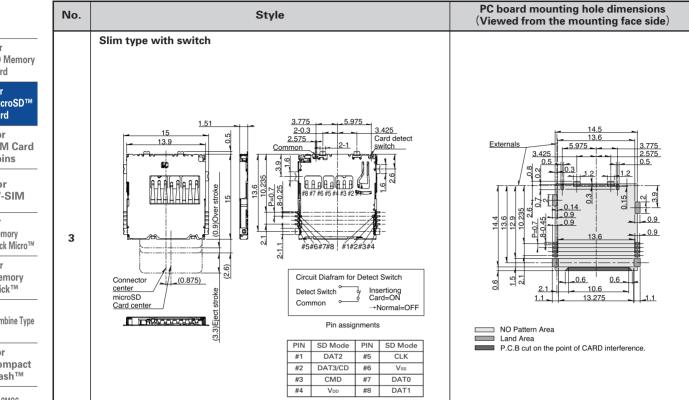
Combine Type

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Dimensions **Reverse mount**

Unit:mm



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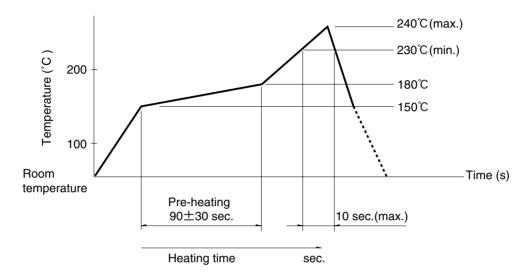
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Soldering Conditions

Example of Reflow Soldering Condition (Reference)

- 1. Heating method: Double heating method with infrared heater.
- 2. Temperature measurement: Thermocouple 0.1 to 0.2 $\phi~$ CA (K) or CC (T) .
- 3. Temperature profile (Surface of products).



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Cautions for using this product

- 1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
- 2. Avoid use of water-soluble soldering flux, since it may corrode the product.
- 3. Check and conform to reflow soldering requirements under actual mass production conditions.
- 4. PC board warping may alter the characteristics. Please take this into consideration when designing patterns and layout.
- 5. The card specifications are provided by the above manufactures. Products by other manufactures may not be compliant with these specifications and are subject to change without prior notice.